

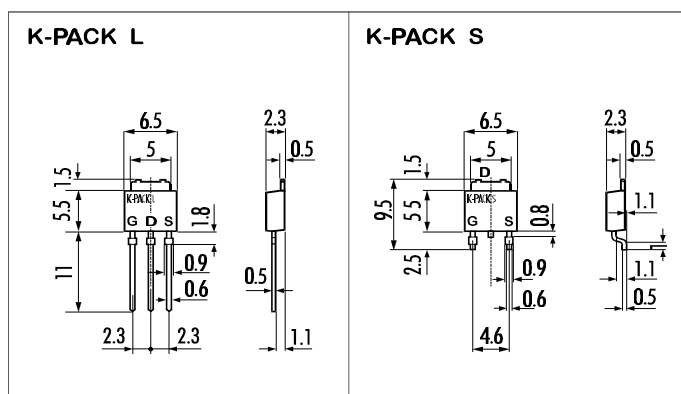
> Features

- High Speed Switching
- Low On-Resistance
- No Secondary Breakdown
- Low Driving Power
- High Voltage
- $V_{GS} = \pm 30V$ Guarantee
- Avalanche Proof

> Applications

- Switching Regulators
- UPS
- DC-DC converters
- General Purpose Power Amplifier

> Outline Drawing

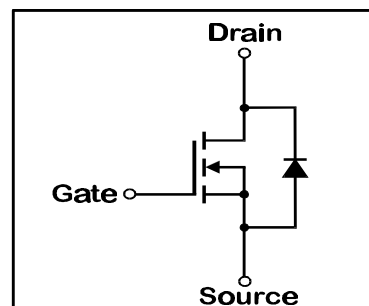


> Maximum Ratings and Characteristics

- Absolute Maximum Ratings ($T_C=25^\circ C$), unless otherwise specified

Item	Symbol	Rating	Unit
Drain-Source-Voltage	V_{DS}	250	V
Drain-Gate-Voltage ($R_{GS}=20K\Omega$)	V_{DGR}	250	V
Continous Drain Current	I_D	4	A
Pulsed Drain Current	$I_{D(puls)}$	16	A
Gate-Source-Voltage	V_{GS}	± 30	V
Max. Power Dissipation	P_D	20	W
Operating and Storage Temperature Range	T_{ch}	150	$^\circ C$
	T_{stg}	-55 ~ +150	$^\circ C$

> Equivalent Circuit



- Electrical Characteristics ($T_C=25^\circ C$), unless otherwise specified

Item	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown-Voltage	$V_{(BR)DSS}$	$I_D=1mA$ $V_{GS}=0V$	250			V
Gate Threshold Voltage	$V_{GS(th)}$	$I_D=1mA$ $V_{DS}=V_{GS}$	2,5	3,0	3,5	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=250V$ $T_{ch}=25^\circ C$		10	500	μA
		$V_{GS}=0V$ $T_{ch}=125^\circ C$		0,2	1,0	mA
Gate Source Leakage Current	I_{GSS}	$V_{GS}=\pm 30V$ $V_{DS}=0V$		10	100	nA
Drain Source On-State Resistance	$R_{DS(on)}$	$I_D=2,0A$ $V_{GS}=10V$		0,8	1,1	Ω
Forward Transconductance	g_{fs}	$I_D=2,0A$ $V_{DS}=25V$	1,0	2,0		S
Input Capacitance	C_{iss}	$V_{DS}=25V$		230	350	pF
Output Capacitance	C_{oss}	$V_{GS}=0V$		70	110	pF
Reverse Transfer Capacitance	C_{rss}	$f=1MHz$		45	70	pF
Turn-On-Time t_{on} ($t_{on}=t_{d(on)}+t_r$)	$t_{d(on)}$	$V_{CC}=150V$ $I_D=4A$ $V_{GS}=10V$ $R_{GS}=10\Omega$		10	15	ns
	t_r			20	30	ns
Turn-Off-Time t_{off} ($t_{off}=t_{d(off)}+t_f$)	$t_{d(off)}$			25	40	ns
	t_f			10	15	ns
Avalanche Capability	I_{AV}	$L = 100\mu H$ $T_{ch}=25^\circ C$	4			A
Continous Reverse Drain Current	I_{DR}				4	A
Pulsed Reverse Drain Current	I_{DRM}				8	A
Diode Forward On-Voltage	V_{SD}	$I_F=2I_{DR}$ $V_{GS}=0V$ $T_{ch}=25^\circ C$		1,0	1,5	V
Reverse Recovery Time	t_{rr}	$I_F=I_{DR}$ $V_{GS}=0V$		110		ns
Reverse Recovery Charge	Q_{rr}	$-dI_F/dt=100A/\mu s$ $T_{ch}=25^\circ C$		0,5		μC

- Thermal Characteristics

Item	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Thermal Resistance	$R_{th(ch-a)}$	channel to air				$^\circ C/W$
	$R_{th(ch-c)}$	channel to case			62,5	$^\circ C/W$

N-channel MOS-FET			
250V	1,1Ω	4A	20W

2SK2292-01L,S

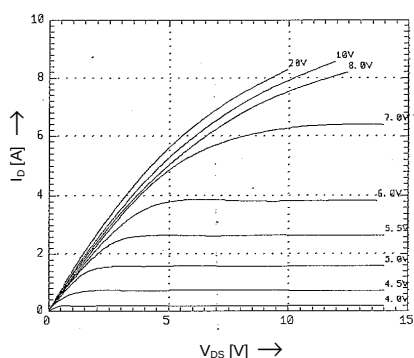
FAP-IIA Series

FUJI
ELECTRIC

> Characteristics

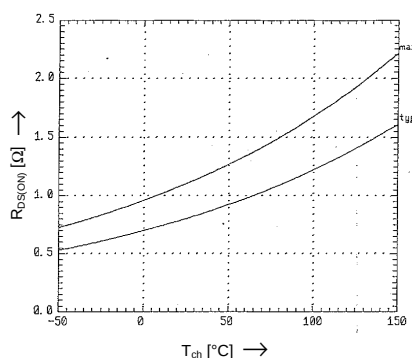
Typical Output Characteristics

$I_D=f(V_{DS})$; 80μs pulse test; $T_C=25^\circ\text{C}$



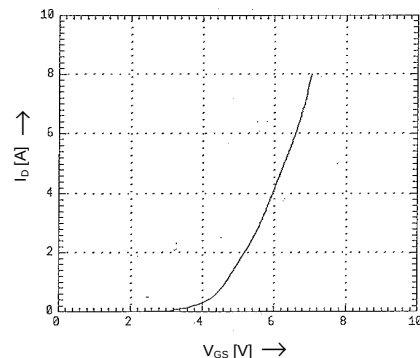
Drain-Source On-State Resistance vs. T_{ch}

$R_{DS(on)}=f(T_{ch})$; $I_D=2\text{A}$; $V_{GS}=10\text{V}$



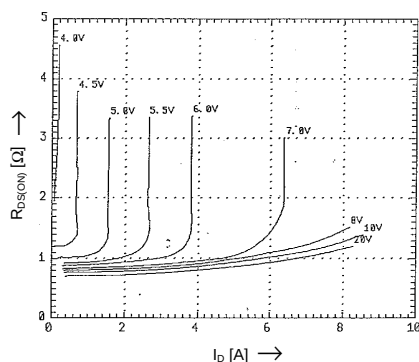
Typical Transfer Characteristics

$I_D=f(V_{GS})$; 80μs pulse test; $V_{DS}=25\text{V}$; $T_{ch}=25^\circ\text{C}$



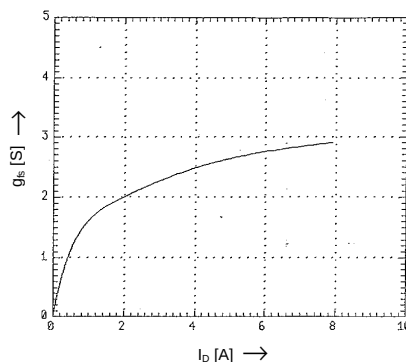
Typical Drain-Source On-State-Resistance vs. I_D

$R_{DS(on)}=f(I_D)$; 80μs pulse test; $T_C=25^\circ\text{C}$



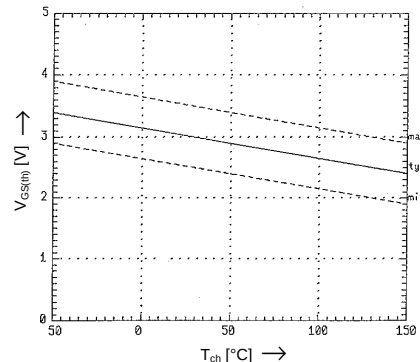
Typical Transconductance

$g_{fs}=f(I_D)$; 80μs pulse test; $V_{DS}=25\text{V}$; $T_{ch}=25^\circ\text{C}$



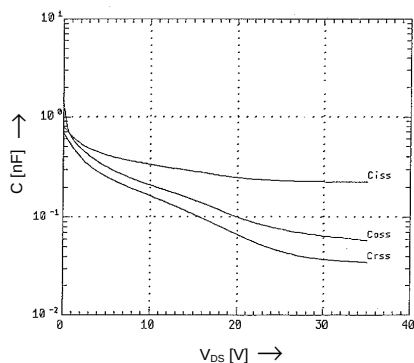
Gate Threshold Voltage vs. T_{ch}

$V_{GS(th)}=f(T_{ch})$; $I_D=1\text{mA}$; $V_{DS}=V_{GS}$



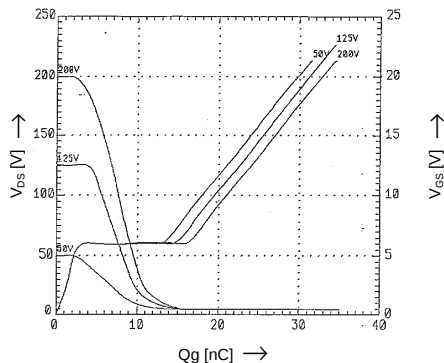
Typical Capacitances

$C=f(V_{DS})$; $V_{GS}=0\text{V}$; $f=1\text{MHz}$



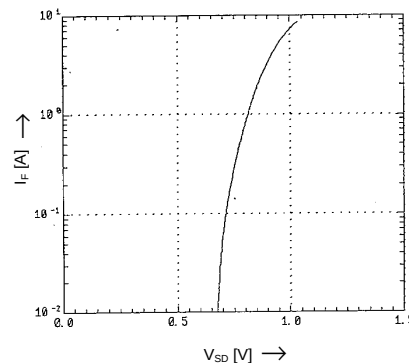
Typical Gate Charge Characteristics

$V_{GS}=f(Q_g)$; $I_D=4\text{A}$



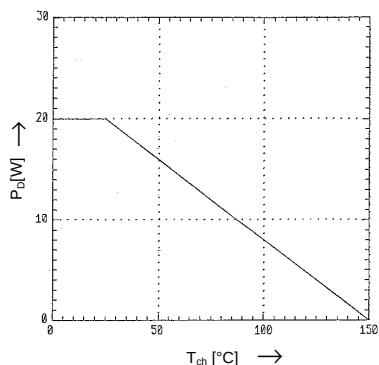
Forward Characteristics of Reverse Diode

$I_F=f(V_{SD})$; 80μs pulse test; $V_{GS}=0\text{V}$



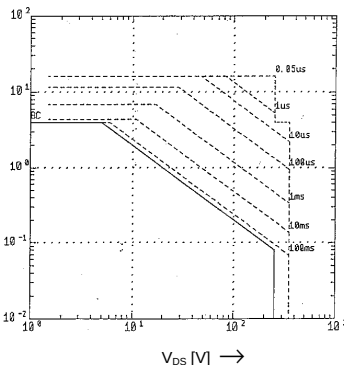
Power Dissipation

$P_D=f(T_C)$



Safe Operation Area

$I_D=f(V_{DS})$; $D=0.01$; $T_C=25^\circ\text{C}$



Transient Thermal impedance

$Z_{th(ch-a)}=f(t)$ parameter: $D=t/T$

